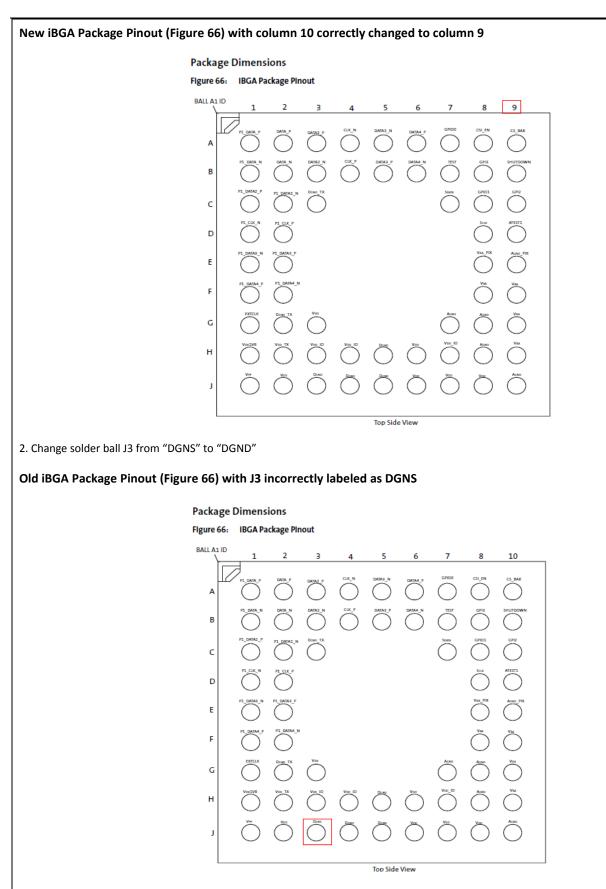
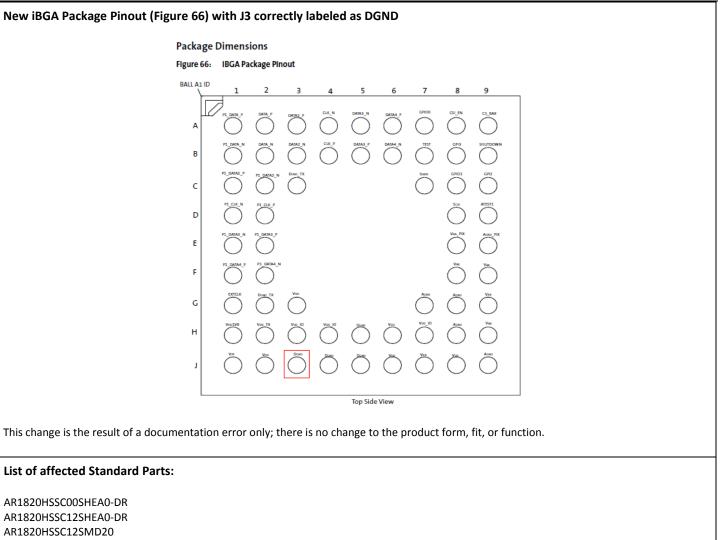


Title of Change:	Datasheet correction for the AR1820, Figure 66 errors.	
Effective date:	15 July 2015	
Contact information:	Contact your local ON Semiconductor Sales Office or <sonya.yip@onsemi.com></sonya.yip@onsemi.com>	
Type of notification:	ON Semiconductor will consider this change accepted.	
Change category:	🗌 Wafer Fab Change 🗌 Assembly Change 🗌 Test Change 🛛 Other	
Change Sub-Category(s): Manufacturing Site Change Manufacturing Process Cha		
Sites Affected: ⊠ All site(s) □ not ap	applicable ON Semiconductor site(s) : External Foundry/Subcon site(s)	
Description and Purpose: It was identified by Field Applications Engineer that iBGA Package Pinout (Figure 66) found in revision G from January 2015 had errors and needed to be updated. In order to correct this, the following changes have been made.		
1. Change column 10 to column 9		
Old iBGA Package Pinout (Figure 66) with incorrect column 10 label		
	Package DimensionIf if	









AR1820HSSC12SMD20 AR1820HSSC31SMD20 AR1820HSSC00SHQAD3-GEVK AR1820HSSC00SHQAH3-GEVB AR1820HSSC12SHQAD3-GEVK AR1820HSSC12SHQAH3-GEVB AR1820HSSC31SMEAD3-GEVK AR1820HSSC31SMEAH3-GEVB